



Material Content Data Sheet



Halogen-Free

Sales Product Name	IRFP1405PBF	Issued	21. July 2021
MA#	MA005539513		
Package	PG-TO247-3-901	Weight*	5733.96 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	14.694	0.26	0.26	2563	2563
leadframe	inorganic material	phosphorus	7723-14-0	1.131	0.02		197	
	non noble metal	iron	7439-89-6	3.771	0.07		658	
	non noble metal	copper	7440-50-8	3,765.728	65.68	65.77	656742	657597
wire	non noble metal	aluminium	7429-90-5	12.283	0.21	0.21	2142	2142
encapsulation	organic material	carbon black	1333-86-4	9.567	0.17		1668	
	plastics	epoxy resin	-	382.680	6.67		66739	
	inorganic material	silicondioxide	60676-86-0	1,521.152	26.53	33.37	265289	333696
leadfinish	non noble metal	tin	7440-31-5	13.948	0.24	0.24	2433	2433
solder	non noble metal	tin	7440-31-5	0.180			31	
	noble metal	silver	7440-22-4	0.225			39	
	non noble metal	lead	7439-92-1	8.597	0.15	0.15	1499	1569
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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